



Material Content Data Sheet



Sales Product Name		TLE9867QXW20		Issued		24. January 2018		
MA#		MA001506240						
Package		PG-VQFN-48-29		Weight*		130.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.70	3.70	37020	37020
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		550	
	non noble metal	iron	7439-89-6	1.433	1.10		11006	
wire	non noble metal	copper	7440-50-8	58.193	44.70	45.87	446880	458574
	noble metal	gold	7440-57-5	0.823	0.63	0.63	6324	6324
encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1392	
	plastics	epoxy resin	-	7.675	5.89		58939	
	inorganic material	silicondioxide	60676-86-0	52.577	40.38	46.41	403755	464086
leadfinish	non noble metal	tin	7440-31-5	2.596	1.99	1.99	19938	19938
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4714	4714
glue	plastics	epoxy resin	-	0.280	0.21		2149	
	noble metal	silver	7440-22-4	0.937	0.72	0.93	7195	9344
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com